	CONNECTING CS INDUSTRIES® international and Part	PC, Bannockb	ourn, Illinois. A	Il rights reserved u ntions.	nder both	This docume level parts, t	ent is a declarat he declaration e	ion of the	e substances sses all lowe	within the r er level mate	nanufacture rials for wh	er listed ite nich the ma	m. Note: if nufacturer l	the item is an as has engineering	ssembly with lowe responsibility.
1752-21.1	IPC Web Site for Inf http://www.ipc.org/	PC-1752 Stand	C-1752 Standard Form Type * Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia					als and Mfg Information				
Supplie	r Information														
Company	name*	Company unique ID			1	Unique ID Authority					Response Date*				
onsemi												2024-05-06			
Contact N	Name	Title - Contact]	Phone - Contact*					Email - Contact*				
Product-	Env-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*		Title - Representative]	Phone - Representative*				Email - Representative*				
Product-	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item MJL4281		Number Mfr Item Name				Effective DateVersionManufacturing2024-05-06KR8		ng Site	Weight*		UOM	Unit Type		
			1AG	AG BIP T0264 NPN 15A 350V						1)737.244	mg	Each		
/Ianufa	ecturing Proccess Information	tion					-								
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 M		J-STD-020 MS	L Rating	Peak Process Body Te		Temperature Max Time at Peak		Temperature Number of Reflow Cy		cles		
Matte Tin (Sn) - annealed		CU Alloy NA			0		С	30		second	s 3				
omments	S														
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.004	mg	Supplier	Silicon (Si)	7440-21-3		0.004	mg
Die Attach	438.49	mg	А	Lead (Pb)	7439-92-1	7a	416.5655	mg
			Supplier	Tin (Sn)	7440-31-5		21.9245	mg
Lead Frame	6869.64	mg	Supplier	Zinc (Zn)	7440-66-6		6.8696	mg
			Supplier	Iron (Fe)	7439-89-6		6.8696	mg
			Supplier	Copper (Cu)	7440-50-8		6855.9009	mg
Mold Compound-Black	3393.27	mg		Brominated epoxy resin	proprietary data		135.7308	mg
			Supplier	Phenolic Resin	Proprietary Data		173.0568	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		44.1125	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2694.2566	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		346.1133	mg
Plating	34.3	mg	Supplier	Tin (Sn)	7440-31-5		34.3	mg
Wire Bond - Al	1.54	mg	Supplier	Aluminum (Al)	7429-90-5		1.54	mg